

Fig. 1 Prior art

Step 1  
wafer out/Probing

Step 2  
Bumping

Step 3  
Flip chip package

Fig. 2

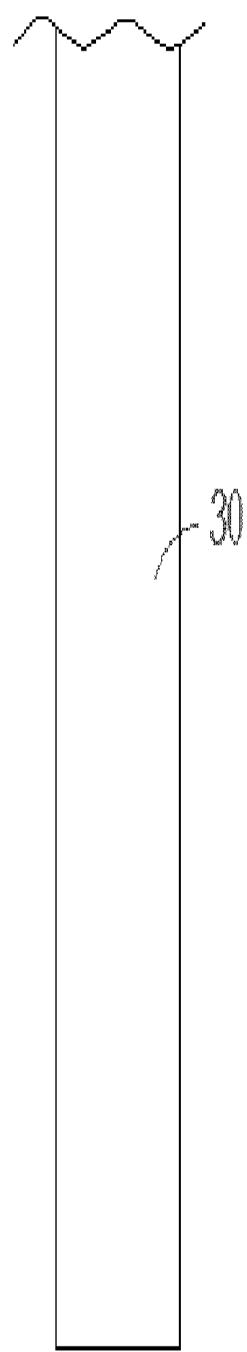


Fig. 3a

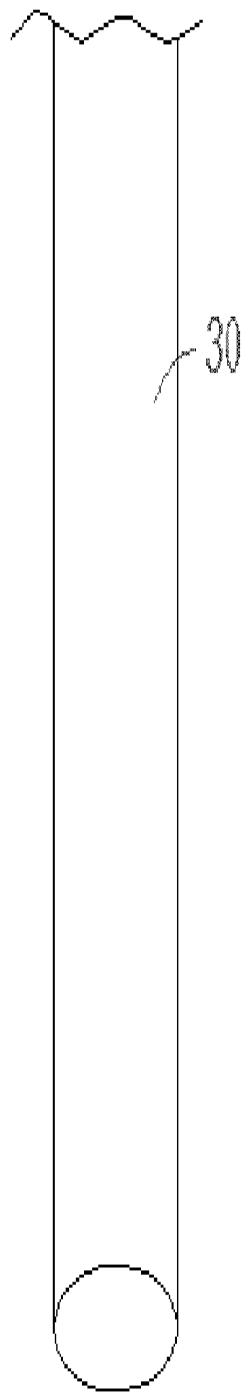
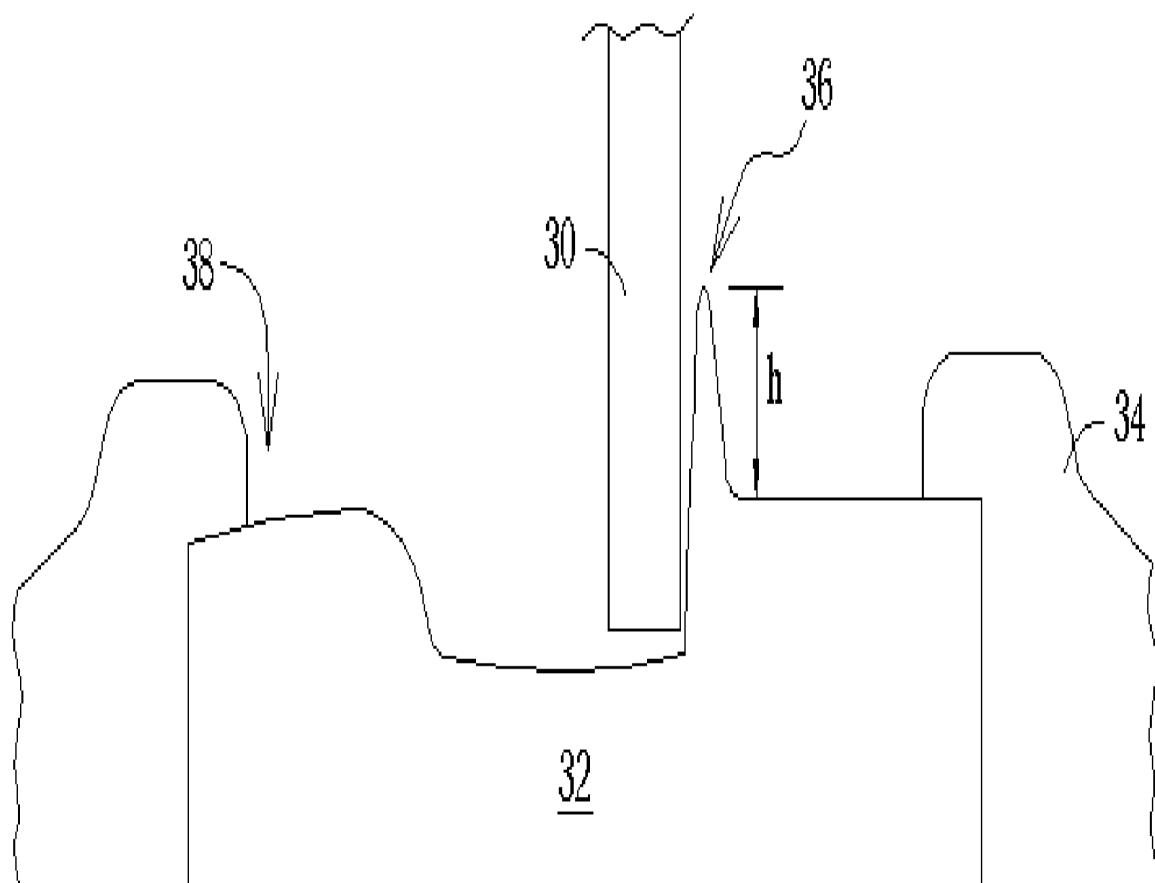


Fig. 3b



40

Fig. 3c

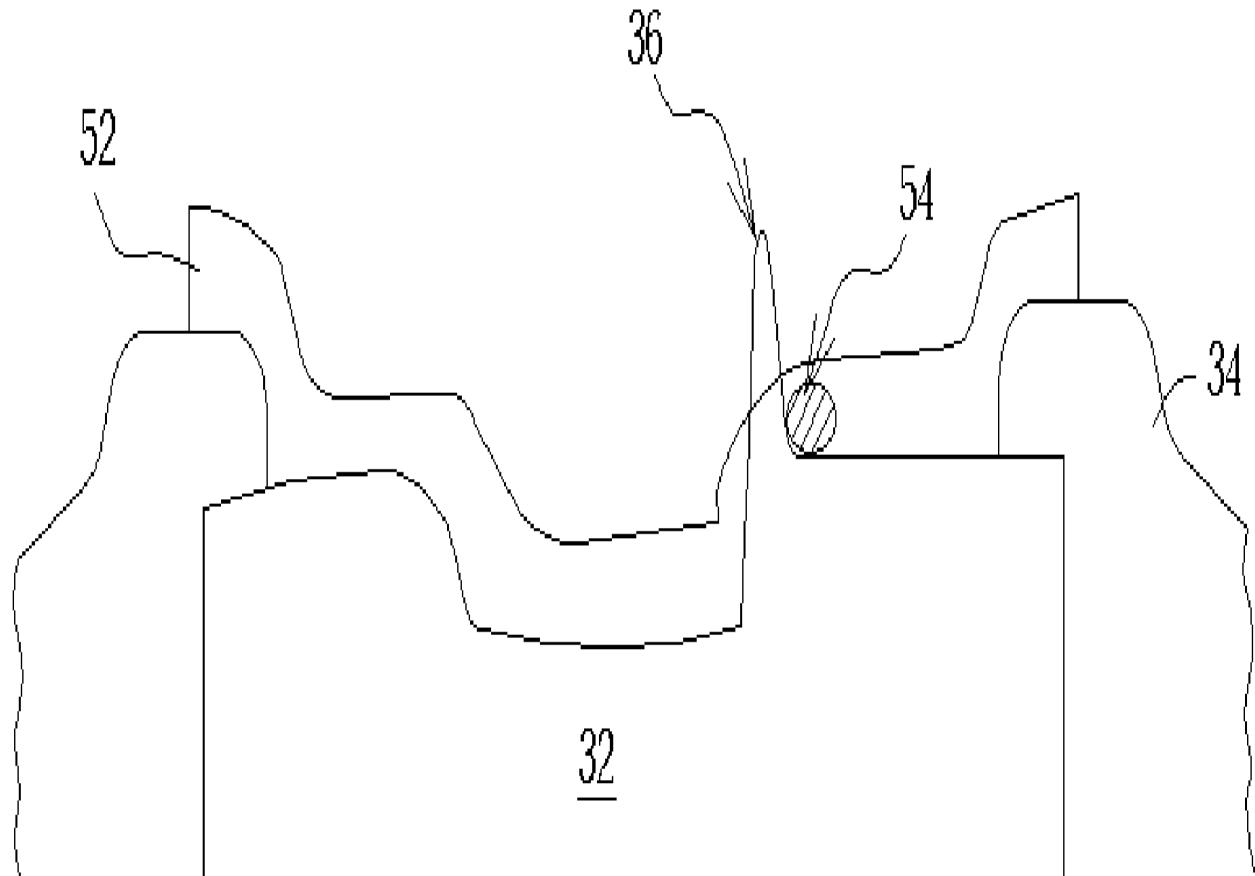


Fig. 3d

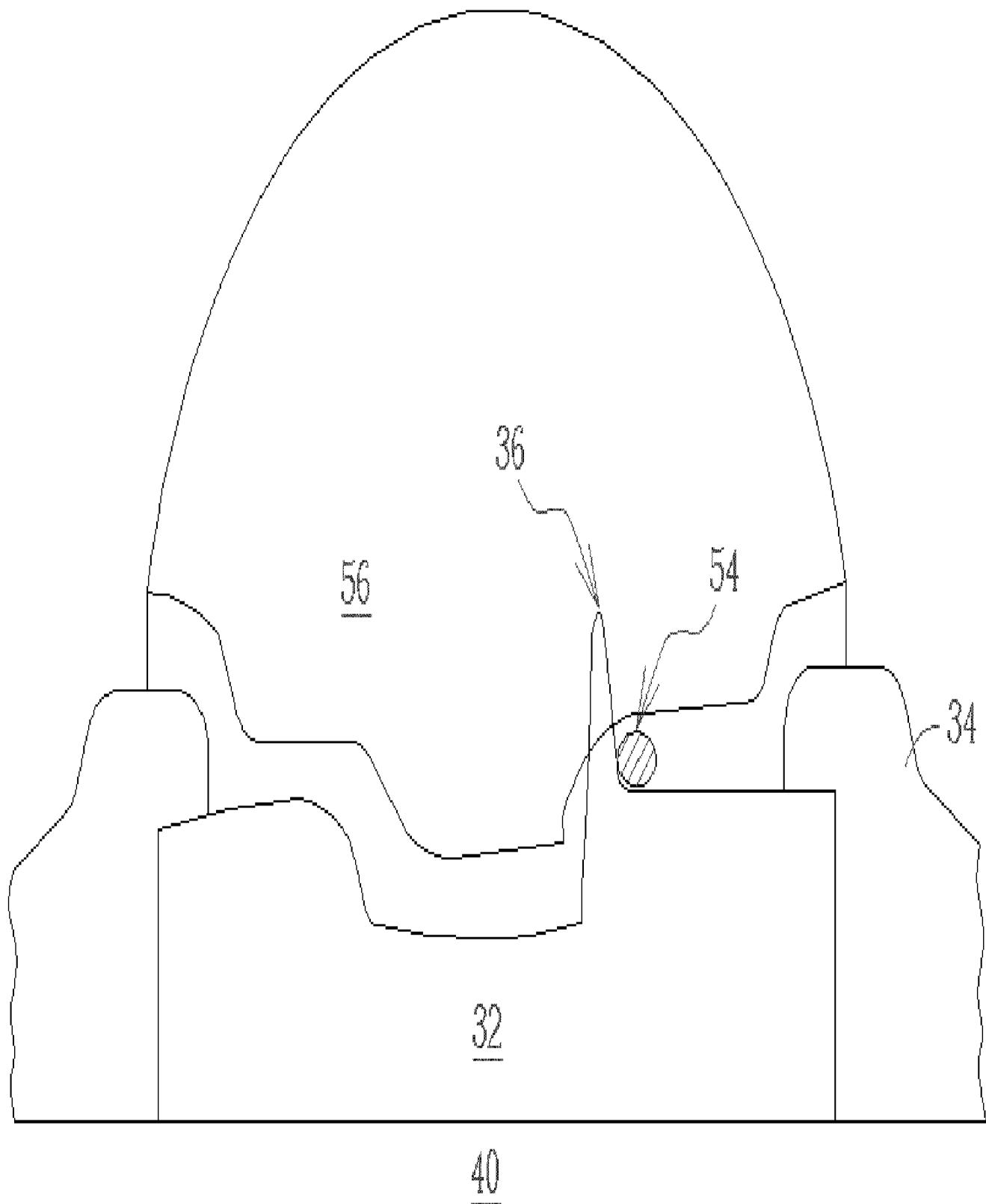


Fig. 3e

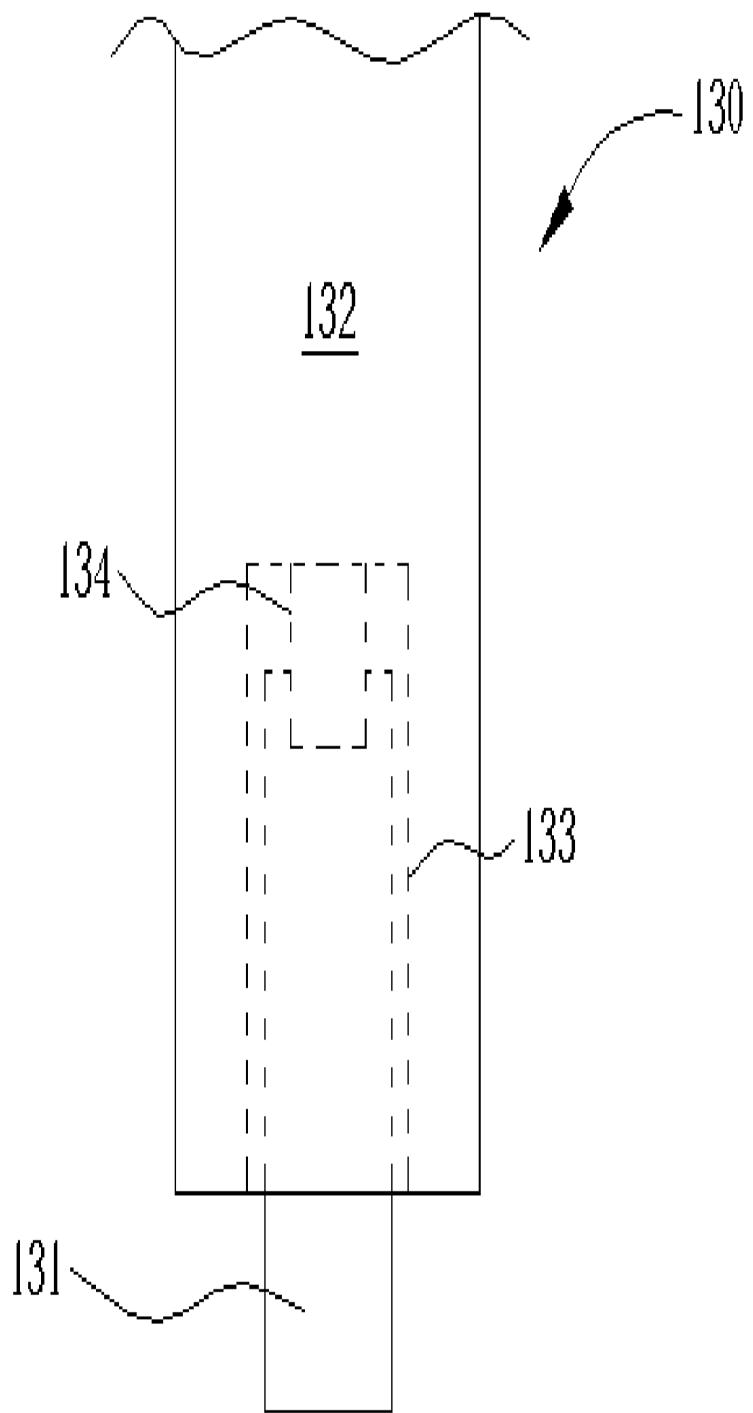


Fig. 4a

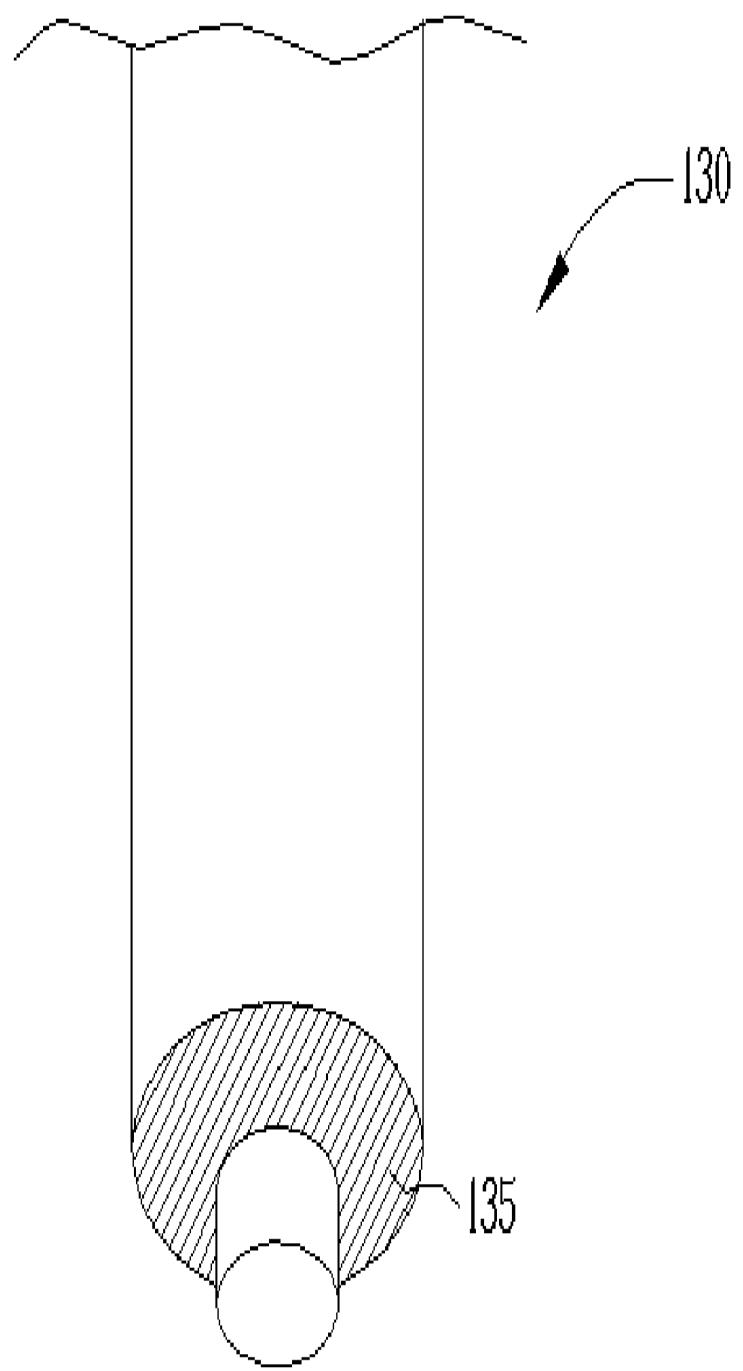


Fig. 4b

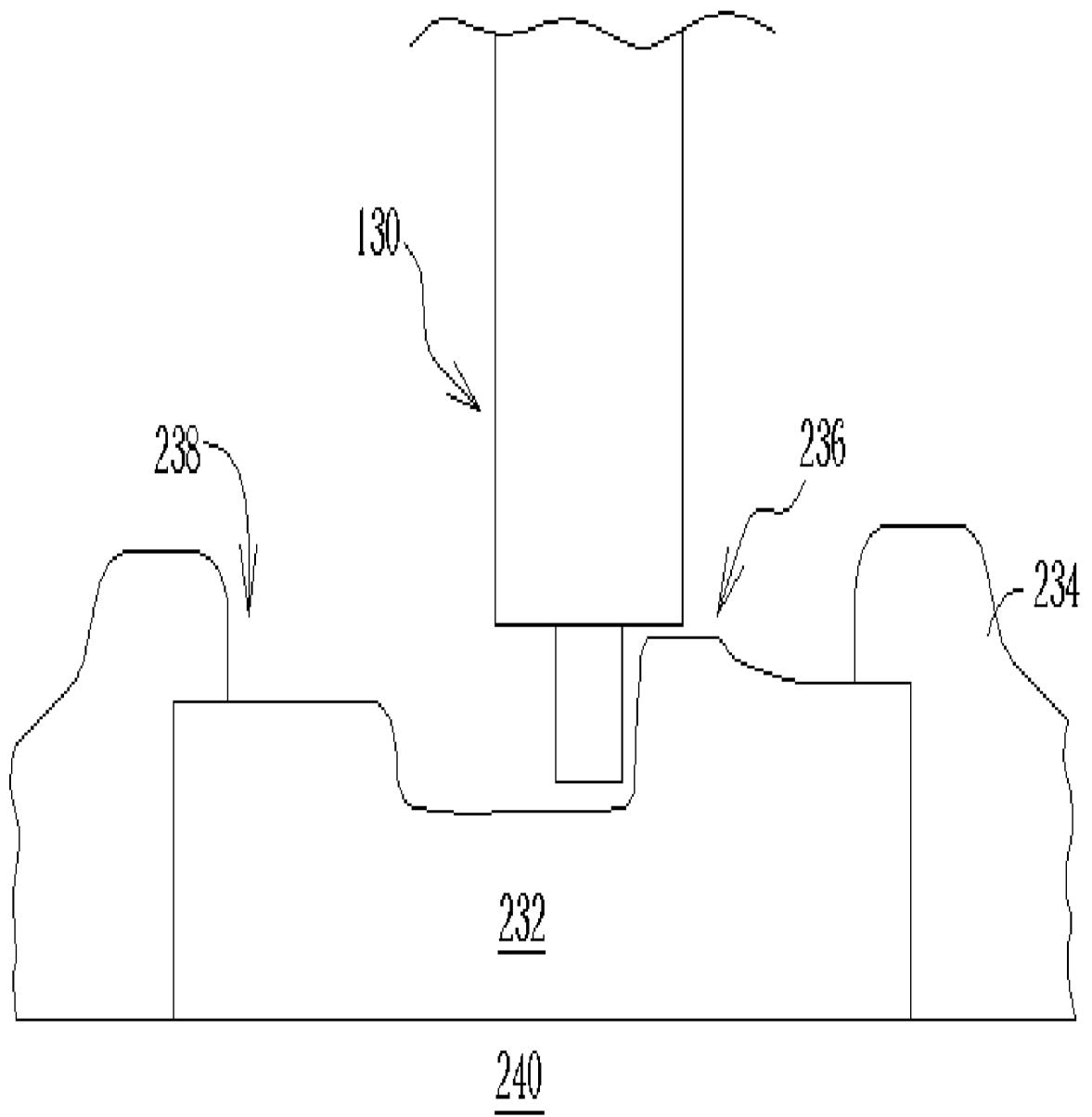


Fig. 4c

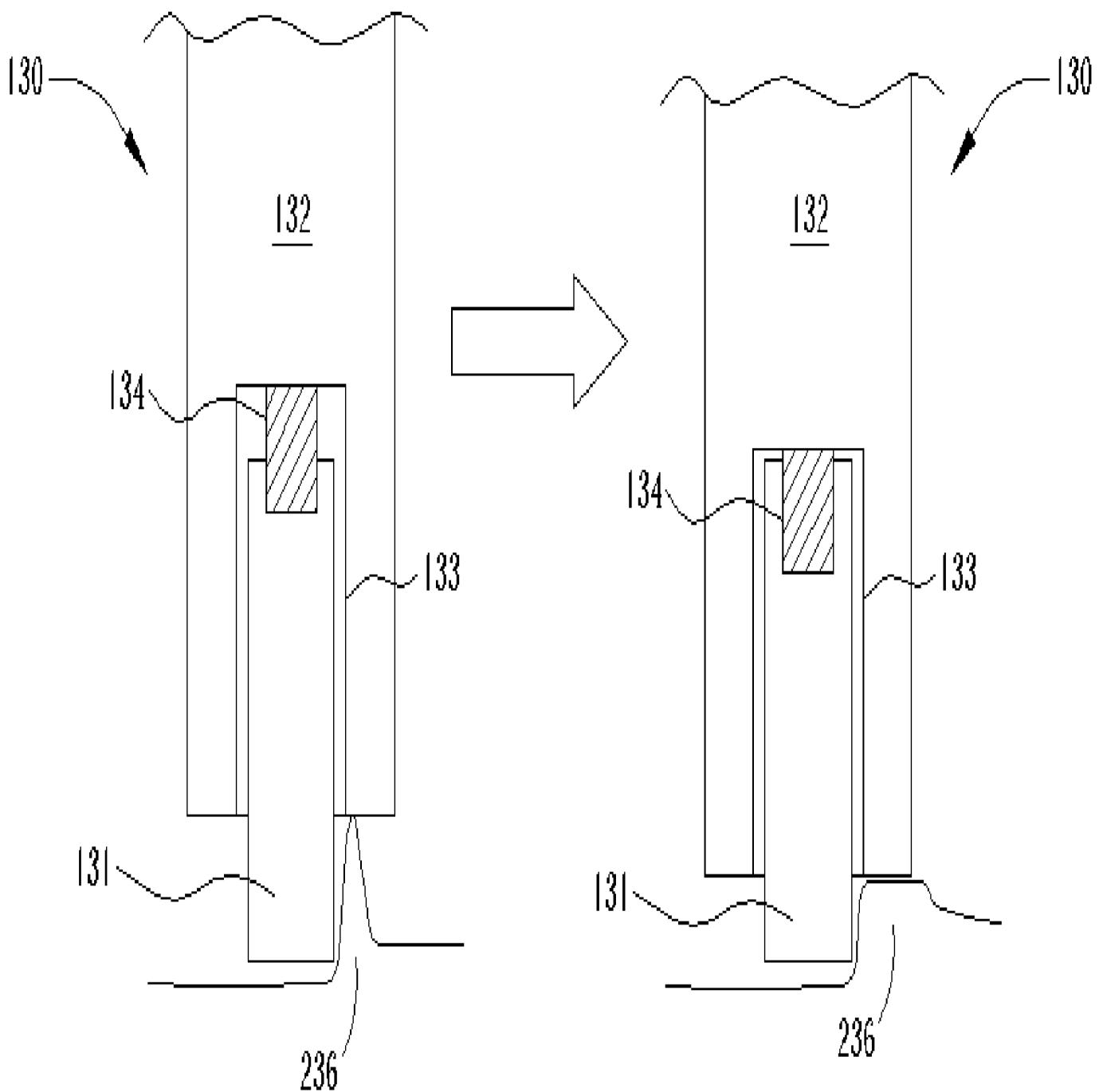
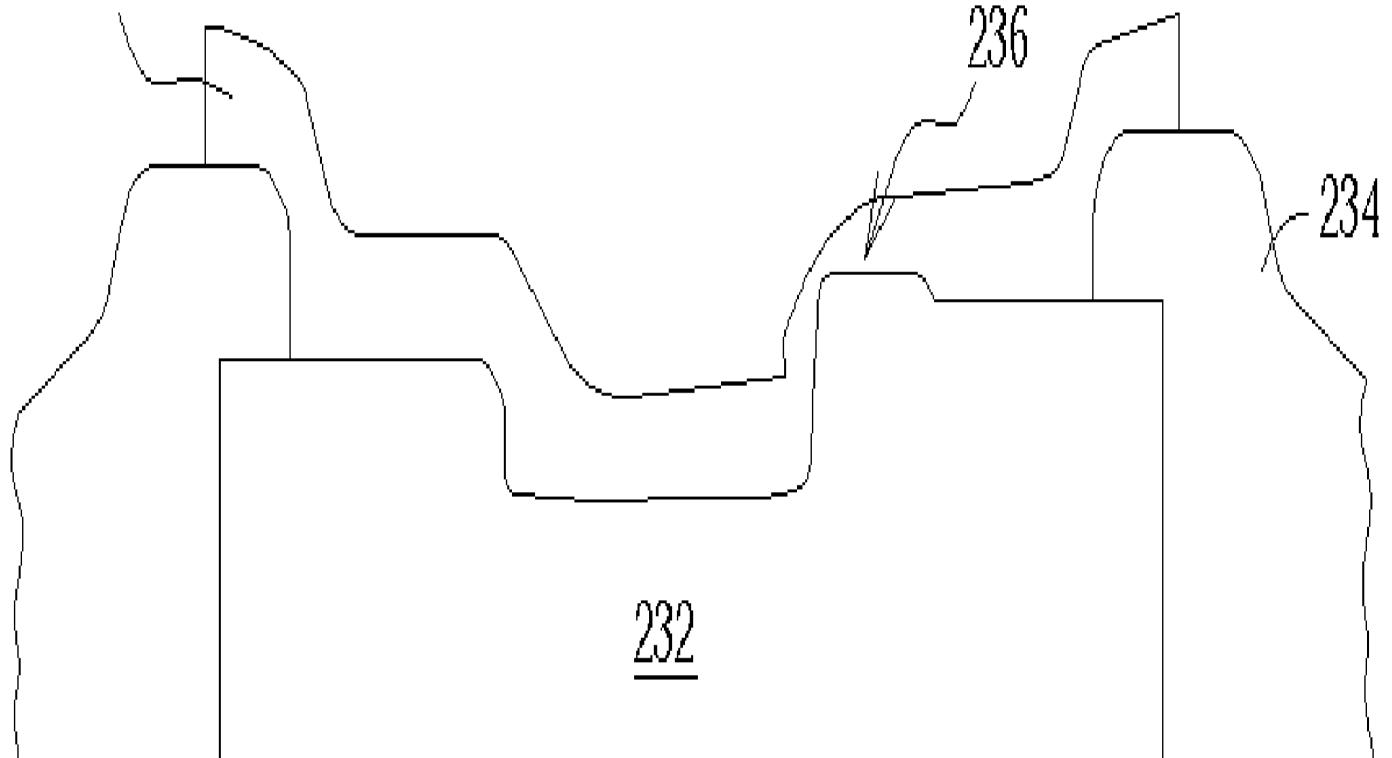


Fig. 4d

352



232

240

Fig. 4e

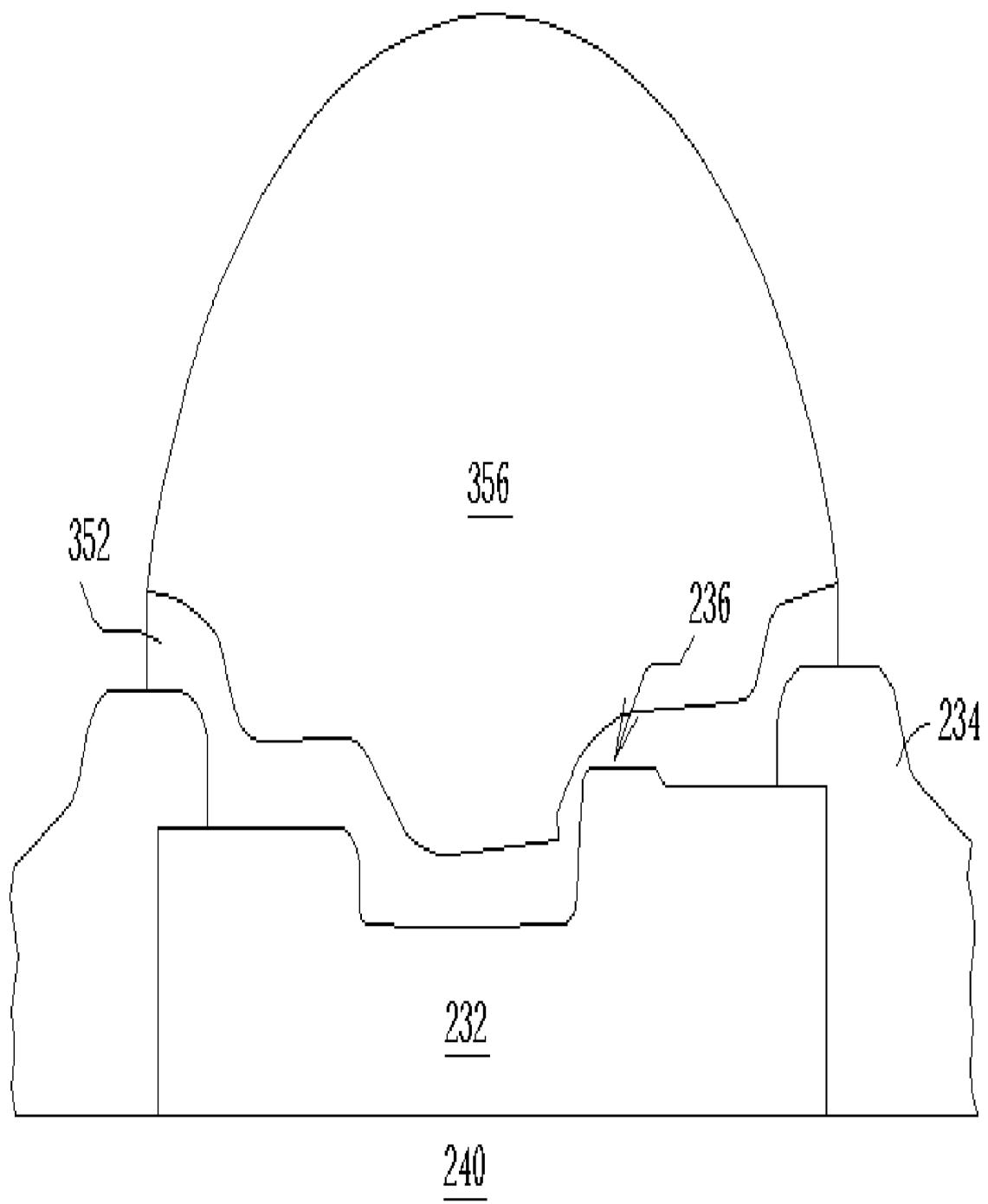


Fig. 4f